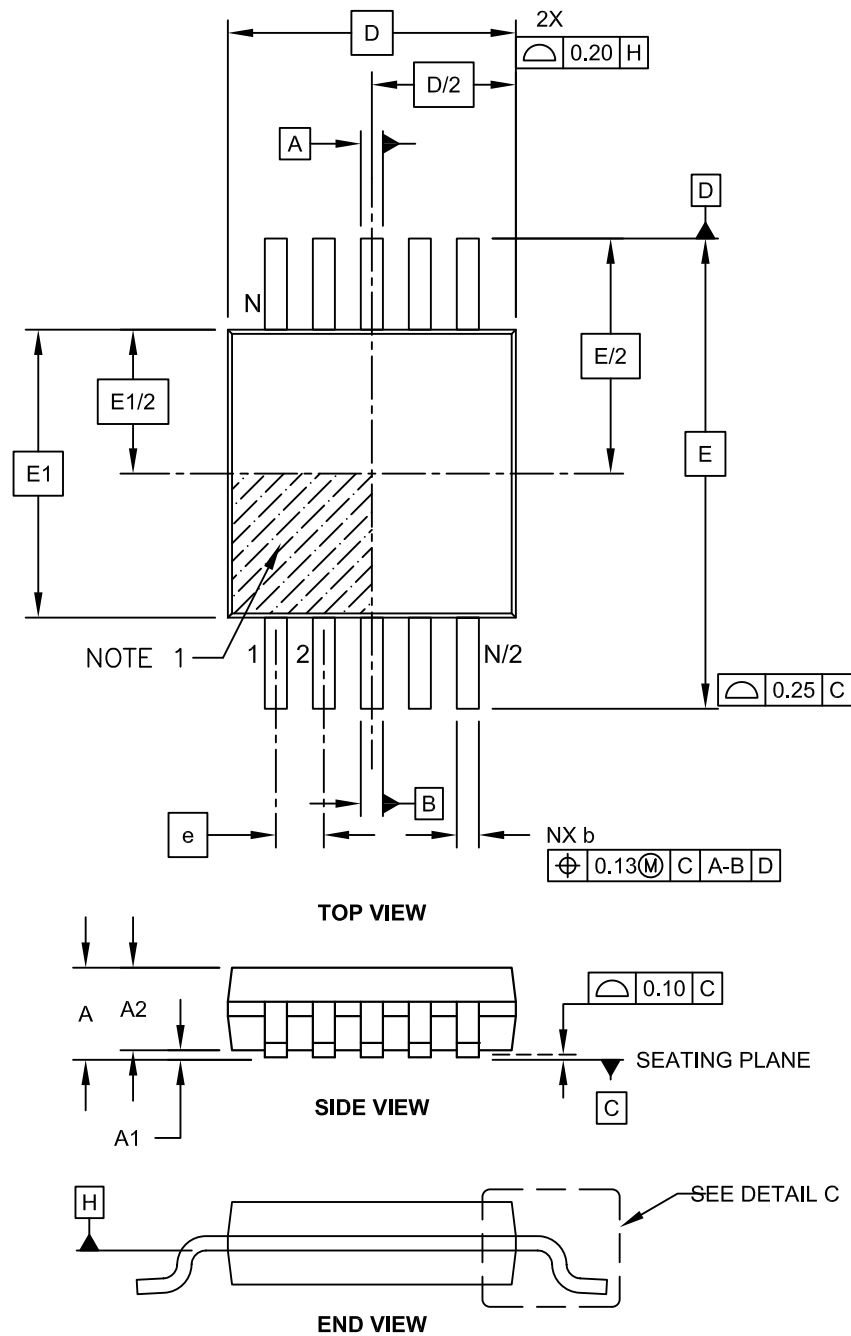


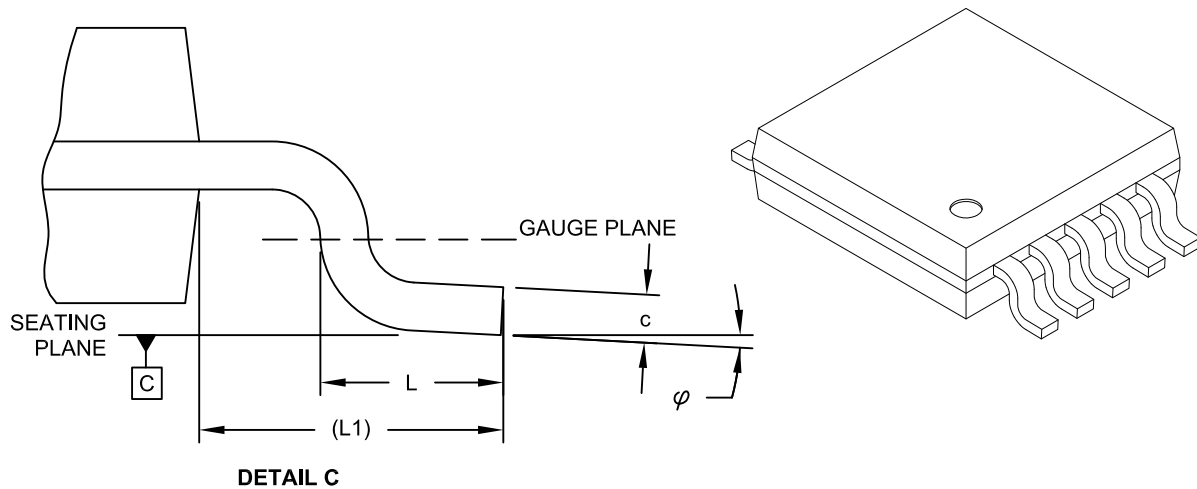
# 10-Lead Plastic Micro Small Outline Package (UN) [MSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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| Units                    |    | MILLIMETERS |      |      |
|--------------------------|----|-------------|------|------|
| Dimension Limits         |    | MIN         | NOM  | MAX  |
| Number of Pins           | N  | 10          |      |      |
| Pitch                    | e  | 0.50 BSC    |      |      |
| Overall Height           | A  | -           | -    | 1.10 |
| Molded Package Thickness | A2 | 0.75        | 0.85 | 0.95 |
| Standoff                 | A1 | 0.00        | -    | 0.15 |
| Overall Width            | E  | 4.90 BSC    |      |      |
| Molded Package Width     | E1 | 3.00 BSC    |      |      |
| Overall Length           | D  | 3.00 BSC    |      |      |
| Foot Length              | L  | 0.40        | 0.60 | 0.80 |
| Footprint                | L1 | 0.95 REF    |      |      |
| Foot Angle               | φ  | 0°          | -    | 8°   |
| Lead Thickness           | c  | 0.08        | -    | 0.23 |
| Lead Width               | b  | 0.15        | -    | 0.33 |

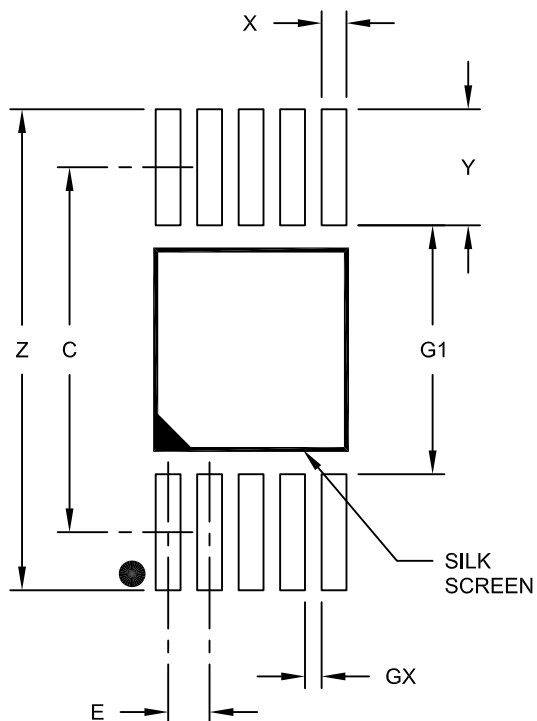
**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-021C Sheet 2 of 2

## 10-Lead Plastic Micro Small Outline Package (UN) [MSOP]

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RECOMMENDED LAND PATTERN

| Units                    |    | MILLIMETERS |      |      |
|--------------------------|----|-------------|------|------|
| Dimension Limits         |    | MIN         | NOM  | MAX  |
| Contact Pitch            | E  | 0.50 BSC    |      |      |
| Contact Pad Spacing      | C  |             | 4.40 |      |
| Overall Width            | Z  |             |      | 5.80 |
| Contact Pad Width (X10)  | X1 |             |      | 0.30 |
| Contact Pad Length (X10) | Y1 |             |      | 1.40 |
| Distance Between Pads    | G1 | 3.00        |      |      |
| Distance Between Pads    | GX | 0.20        |      |      |

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2021A